

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
11	BRS	L11	9825	(seed\$4 or Cu or copper) and (Ni or nickel or Au or gold or plat\$4 or electroplat\$4) and (UBM or metallurgy or underbump or (under adj bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/10/20 21:31	
12	BRS	L12	2539	11 and (pad or bondpad or ((wir\$6 or bump or ball) near3 bond\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/10/20 21:31	
14	BRS	L14	2304	12 and (semiconductor or chip or die or IC or (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2004/10/20 21:32	